

# A New GEM Module for the LPTPC

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## Introduction



### Maximum Sensitive Area

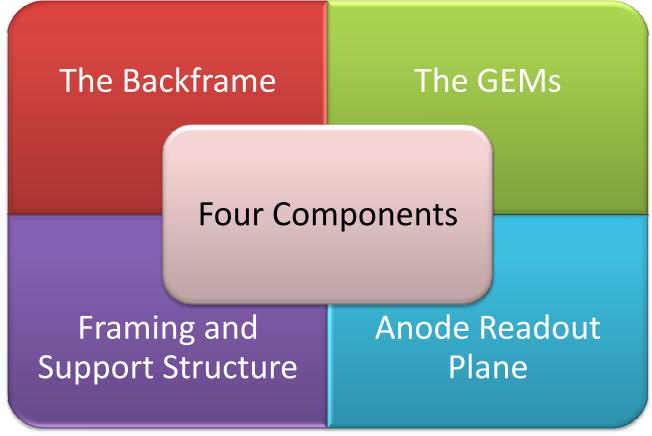
### Gain Uniformity between 5/10%

- To be further increased with calibration efforts
- Good dE/dx resolution

Spatial resolution under 100 µm

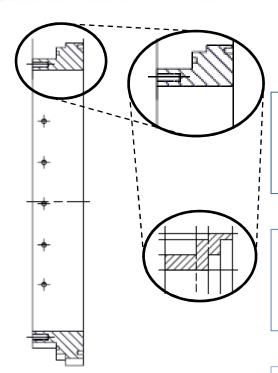
# Introduction





# The new backframe: Design





### Goal

• To increase the available space on the connector side of the readout plane

### No predicted negative effect

• The element which has been thinned does only support the pad plane

### Height of the module to be estabilished

• The total heigth of the module is to be estabilished once we decide for the total thickness of the GEM stack

# The new backframe: Production



### Site

 The production of the backframe will be performed at the University of Hamburg workshop

### Materials

- The recommended for the production of the module is the alloy Aluminum 6061 T651
- The workshop do not have that material readily available
- We are going to use AlMg4,5MN (Dogal 5080) for the first tests

# Frame and Support System: Issues



### Reduce the unsupported areas

- Gain uniformity limited by the GEM sagging
- To reduce the sagging we must limit the unsupported areas of the GEM

### Increase the sensitive area

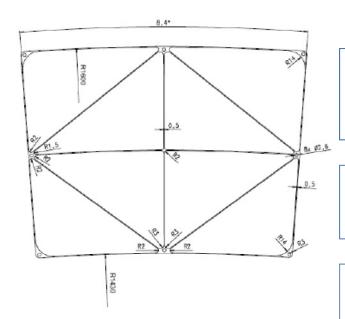
- Sensitive area limited by the presence of supporting materials
- To increase the sensitive area we need to reduce the width of the framing and supporting structure

### Choose a stiffer material than GRP

- To meet both requirements we need an insulating material which can be made thinner remaining as resistent as a normal GRP frame
- Alumina Ceramics is almost 4 times stiffer than GRP and may be machined with widths of 0.5 mm

# Frame and Support System: Design





#### Modular structure

- Every GEM can be separately framed
- The framed GEM can be piled up to form the stack using "ungemmed" frames as spacers

#### 0.5 mm width

- The external frame and the internal grid structure are 0.5 mm wide
- There are 6 strong points for the mounting of the support structure

#### Mandatory horizontal bar

• The horizontal bar presence depends on the mandatory segmentation of the GEM electrodes

#### **Grid patterns**

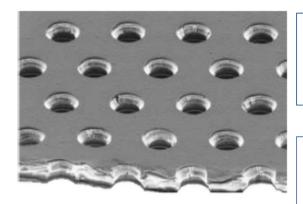
- Many grid patterns have been considered
- Each grid emphasize a specific requirement
- E.g. The grid shown is the stiffer design considered

#### Production

• We got in touch with a production firm and we are evaluating the feasibility of the project

# The GEMs: Design





#### **Custom GEM**

Specifically designed to get the maximum sensitive area

### Produced by CERN

- 50 µm kapton foil
- Chemical etching

### Standard hole size and pitch

- 70 µm hole size
- 140 µm hole pitch

### 2 or 4-fold electrode segmentation

- A 2-fold segmentation will increase the sensitive area
- A 4-fold segmentation will increase the operation safety

# The GEM Stack: Features



#### Three GEM + possible gate

- Three GEM stack
- Optional fourth module (gating)
- The gate may be both GEM or wire based

#### Induction gap

- ullet Small induction gap o better time resolution
- The induction gap effect lower than other effects

### Transfer gap

- Transfer gaps and fields influence the defocussing of the stack
- The defocussing and the pad size influence the point resolution

#### Ion backdrift

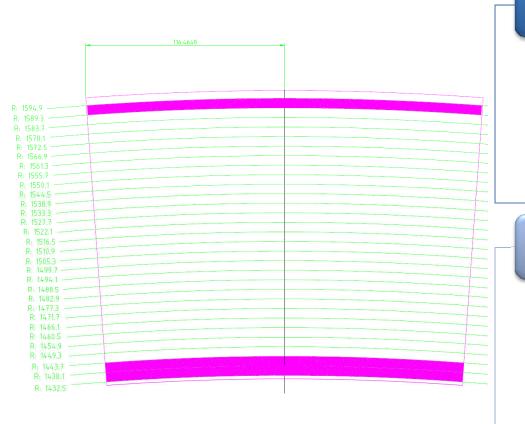
• Influenced by the fields and of the potential across the GEMs

#### Numbers not yet available

• I've not yet done all the calculation and simulation to find the best compromise

# **Anode Readout Plane: Features**





### Structural Features

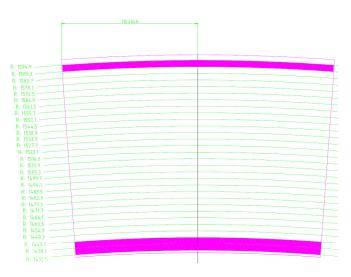
- Ensure gas tightness
- Support the GEM stack
- Provide power to the GEM stack

### Readout Features

- Pad readout
- Maximum possible sensitive area
- Readout by ALTRO electronics

# Anode Readout Plane: Design





### In collaboration with Bonn University

- The design is still in his infancy
- Using the data acquired testing the Bonn GEM module

### Pad size

- (1.1 ÷ 1.25) x (5.6 ÷ 5.8) mm
- 28 rows
- Row gaps aligned with the GEM segmentation gap

### **GEM** Power supply

- Supplied from power pads on the PCB itself
- Using the ceramic structure to separate the power from the readout pads

# Something more: new measurement



### **Gain Calibration**

- Beam calibration
- Laser calibration
- Radioactive source calibration

### Gate efficiency

Confront the efficiency of GEM and wire gates

### Ion Backdrift Measurement

• We need the equipment to perform this measurements on the LP

# **Conclusions**



#### Module Backframe

- First design ready
- Looking for production solutions

#### **Ceramic Framing**

- First design ready
- Design to be updated using producers feedback

#### **GEMs**

- First design ready
- Getting feedback from CERN to update this design

### Anode Readout Plane

Design just beginning

### Other ideas

- Compare gating modules
- Test the gain homogeneity of the modules
- Measure the ion backdrift in the TPC